







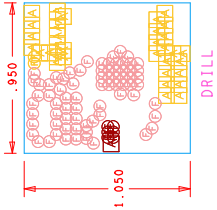


PHYSICAL BOARD DIMENSIONS  
& LAYER STRUCTURE

	SILK TOP	silkt.art
	MASK TOP	smaskt.art
	(TOP)COMPONENT	layer1.art
	LAYER 2	layer2.art
	LAYER 3	layer3.art
	(BOTTOM) SOLDER	layer4.art
	MASK BOTTOM	smaskb.art
	SILK BOTTOM	silkb.art

.062" +/- 10%



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
⊕	11.0	PLATED	81
⊞	12.0	PLATED	35

NOTES:

1. THIS BOARD IS RoHS COMPLIANT.
2. PRINTED WIRING BOARD DESIGN AND ACCEPTANCE CRITERIA SHALL BE IAW WITH THE REQUIREMENTS OF IPC-D-275 AND IPC-A-600.
3. MATERIAL: FR4 (RoHS COMPLIANT), 1 OZ COPPER.
4. APPLY SOLDER MASK, BOTH SIDES OVER BARE COPPER IAW IPC-SM-840, CLASS 2 (LPI) (BLUE MASK).
5. ALL PATTERNS ARE VIEWED FROM THE PRIMARY SIDE LOOKING THROUGH THE BOARD.
6. UNLESS OTHERWISE SPECIFIED ALL HOLE DIAMETERS ARE AFTER PLATING.
7. APPLY SILKSCREEN USING WHITE NON-CONDUCTIVE EPOXY BASED INK.
8. PWB MUST BE 100% ELECTRICALLY TESTED FOR SHORTS AND CONTINUITY. USE NETLIST PROVIDED ISL73006SLHDEMO3ZA\_IPC356\_IPC IAW IPC-D-356.
9. MARK DATE CODE AND MANUFACTURES IDENTIFICATION ON SOLDER SIDE PER IPC-6011 AND IPC-6012.
10. TOLERANCE ON ALL DRILL HOLES SHALL BE IAW IPC-D-2221 & 2222 UNLESS OTHERWISE SPECIFIED.
11. INTERSIL LOGO USED ON THIS DESIGN PLEASE DO NOT CHANGE TO RENESAS.
12. ALL 11 MIL VIA'S ARE TO BE THERMAL EPOXY FILLED AND CAPPED.

Drawn By: <b>Tim Klemann</b>	Date Drawn: <b>12/21/2023</b>	Engineer: <b>Larry Gough</b>
Released By:	Date Released:	
Updated By:	Date Updated:	
		MASK# <b>HDWR ID</b> <b>REV.</b> <b>A</b>
		FILENAME: <b>\\ISL73006SLH\\ISL73006SLHDEMO3ZA</b> SHEET <b>1 of 1</b>
<b>ISL73006SLH</b> <b>DEMO3 BOARD</b> <b>LAYOUT</b>		